

LMS75LBC176 Differential Bus Transceivers General Description

The LMS75LBC176 is a differential bus/line transceiver designed for bidirectional data communication on multipoint bus transmission lines. It is designed for balanced transmission lines. It meets TIA/EIA RS485 and ISO 8482:1987(E). The LMS75LBC176 combines a TRI-STATE™ differential line driver and differential input receiver, both of which operate from a single 5.0V power supply. The driver and receiver have an active high and active low enable, respectively, that can be externally connected to function as a direction control. The driver and receiver differential inputs are internally connected to form differential input/output (I/O) bus ports that are designed to offer minimum loading to bus whenever the driver is disabled or when $V_{CC} = 0V$. These ports feature wide positive and negative common mode voltage ranges, making the device suitable for multipoint applications in noisy environments. The LMS75LBC176 is available in a 8-Pin SOIC package. It is a drop-in socket replacement to TI's SN75LBC176.

Features

- Bidirectional transceiver
- Meet ANSI standard RS-485
- Low skew, 6ns
- Low supply current, 8mA (max)
- Wide input and output voltage range
- High output drive capacity ±60mA
- Thermal shutdown protection
- Open circuit fail-safe for receiver
- Receiver input sensitivity ±200mV
- Receiver input hysteresis 10mV (min.)
- Single supply voltage operation, 5V
- Glitch free power-up and power-down operation
- Pin and functional compatible with TI's SN75LBC176
- 8-Pin SOIC

Applications

- Network hubs, bridges, and routers
- Point of sales equipment (ATM, barcode readers,...)
- Industrial programmable logic controllers
- High speed parallel and serial applications
- Multipoint applications with noisy environment



A typical multipoint application is shown in the above figure. Terminating resistors, RT, are typically required but only located at the two ends of the cable. Pull up and pull down resistors maybe required at the end of the bus to provide failsafe biasing. The biasing resistors provide a bias to the cable when all drivers are in TRI-STATE, See National Application Note, AN-847 for further information.

MS75LBC176 Differential Bus Transceivers

Connection Diagram



Ordering Information

Package	age Part Number Package Marking Transport Media		NSC Drawing	
	LMS75LBC176M		Rail	M08A
8-Pin SOIC	LMS75LBC176MX	LMS75LBC176 -	2.5k Units Tape and Reel	- WUOA

Truth Table

DRIVER SEC	CTION			
RE	DE	DI	A	В
Х	Н	Н	Н	L
Х	Н	L	L	Н
Х	L	Х	Z	Z
RECEIVER S	SECTION	·	·	
RE	DE	A	-B	RO
L	L	≥ +(Н	
L	L	≤ -(L	
Н	Х	Х		Z
L	L	OPEN *		Н

Note: * = Non Terminated, Open Input only

X = Irrelevent

Z = TRI-STATE

H = High level

L = Low level

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage, V _{CC} (Note 2)	7V
Voltage Range at Any Bus	
Terminal	-7V to 12V
Input Voltage, V_{IN} (DI, DE, or \overline{RE})	–0.3V to V _{CC} + 0.3V
Package Thermal Impedance, θ_{JA}	125C/W
Junction Temperature (Note 3)	150°C
Operating Free-Air Temperature	
Range, T _A	0°C to 70°C
Storage Temperature Range	–65°C to 150°C
Soldering Information	
Infrared or Convection (20 sec.)	235°C
ESD Rating (Note 4)	2KV

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	Min	Nom	Max	
Supply Voltage, V _{CC}	4.75	5.0	5.25	V
Voltage at any Bus Terminal			12	V
(Separately or Common Mode)			-7	
V _{IN} or V _{IC}				
High-Level Input Voltage, V _{IH}	2			V
(Note 5)				
Low-Level Input Voltage, V _{IL}			0.8	V
(Note 5)				
Differential Input Voltage, V _{ID}			±12	V
(Note 6)				
High-Level Output				
Driver, I _{OH}			-60	mA
Receiver, I _{OH}			-400	μA
Low-Level Output				
Driver, I _{OL}			60	mA
Receiver, I _{OL}			8	mA

Electrical Characteristics

 $V_{CC} = 5V$, $T_A = 0^{\circ}C$ to $70^{\circ}C$

Symbol	Parameter	Conditions		Min	Тур	Мах	Units	
Driver Sec	tion							
V _{CL}	Input Clamp Voltage	I ₁ = -18mA				-1.5	V	
Vo	Output Voltage	I _O = 0		0		6	V	
V _{od1}	Differential Output Voltage	I _O = 0		1.5		6	V	
V _{od2}	Differential Output Voltage	$R_L = 54\Omega$		1.5		5	V	
V _{OD3}	Differential Output Voltage	$V_{\text{TEST}} = -7V$ to 12V		1.5		5	V	
ΔV_{OD}	Change in Magnitude of Differential Output Voltage (Note 8)	$R_L = 54\Omega \text{ or } 100\Omega$				±0.2	V	
V _{oc}	Common-Mode Output Voltage	$R_L = 54\Omega \text{ or } 100\Omega$				3 -1	V	
ΔV_{OC}	Change in Magnitude of Differential Output Voltage (Note 8)	$R_L = 54\Omega$ or 100Ω				±0.2	V	
lo	Output Current	Output Disabled (Note 8)	$V_{O} = 12V$ $V_{O} = -7V$			1 -0.8	mA	
I _{IH}	High-Level Input Current	V _{IN} = 2.4V				-100	μΑ	
I _{IL}	Low-Level Input Current	V _{IN} = 0.4V				-100	μΑ	
I _{OSD}	Short-Circuit Output Current	$V_{O} = -7V$				-250		
		$V_{O} = 0$ $V_{O} = V_{CC}$				-150	mA	
						250		
		V _O = 12V				250	1	
I _{CC}	Supply Current	$V_{IN} = 0$ or V_{CC} , No Load	Receiver Disabled and Driver Enabled			8	mA	
			Receiver and Driver Disabled			8		

Symbol	Parameter	Condition	าร	Min	Тур	Max	Units
Switching	Characteristics	I				1	
t _d (OD)	Differential Output Delay Time	R_L = 54 Ω , C_L = 50pF		3		25	ns
t _t (OD)	Differential Output Transition Time	$R_L = 54\Omega, C_L = 50pF$			8		ns
t _{sk(p)}	Pulse Skew, (It _{d(ODH)} - t _{d(ODL)} I)	$R_L = 54\Omega, C_L = 50pF$			0	6	ns
t _{PZH}	Output Enable Time to High Level	$R_{L} = 110\Omega, C_{L} = 50pF$				35	ns
t _{PZL}	Output Enable Time to Low Level	$R_L = 110\Omega, C_L = 50pF$				35	ns
t _{PHZ}	Output Disable Time from High Level	$R_L = 110\Omega, C_L = 50pF$				60	ns
t _{PLZ}	Output Disable Time from Low Level	$R_L = 110\Omega, C_L = 50pF$				35	ns
Receiver S	Section						
V_{TH+}	Positive-Going Input Threshold Voltage	$V_{\rm O} = 2.7 V, \ I_{\rm O} = -0.4 \text{mA}$	·			0.2	V
V_{TH-}	Negative-Going Input Threshold Voltage	$V_{O} = 0.5V, I_{O} = 8mA$		-0.2			V
ΔV_{TH}	Hysteresis Voltage (V _{TH+} - V _{TH-})			10			mV
V _{CL}	Enable-Input Clamp Voltage	$I_1 = -18mA$				-1.5	V
V _{он}	High-Level Output Voltage	$V_{ID} = 200 \text{mV}, I_{OH} = -400 \mu \text{A}$		2.7			V
V _{OL}	Low-Level Output Voltage	$V_{ID} = -200 \text{mV}, I_{OL} = 8 \text{m}$	$V_{ID} = -200 \text{mV}, \ I_{OL} = 8 \text{mA}$			0.45	V
l _{oz}	High-Impedance-State Output Current	$V_{\rm O}$ = 0.4V to 2.4V				±20	μA
I _{IN}	Line Input Current	Other Input = 0V, See (Note 8)	$V_{IN} = 12V$ $V_{IN} = -7V$			1 -0.8	mA
I _{IH}	High-Level Enable-Input Current	V _{IH} = 2.7V				-100	μΑ
IIL	Low-Level Enable-Input Current	$V_{IL} = 0.4V$				-100	μA
R _{IN}	Input Resistance			12			kΩ
I _{cc}	Supply Current	V _{IN} = 0 or V _{CC} , No Load	Receiver Enabled and Driver Disabled			8	mA
			Receiver and Driver Disabled			8	
Switching	Characteristics						
T _{PLH}	Propagation Delay Time, Low-to High-Level Single-Ended Output	$V_{ID} = -1.5V$ to 1.5V		8		33	ns
T _{PHL}	Propagation Delay Time, High-to Low-Level Single-Ended Output	$V_{ID} = -1.5V$ to 1.5V		8		33	ns
t _{sk(p)}	Pulse Skew (It _{PLH} - t _{PHL} I)	V _{ID} = -1.5V to 1.5V			2		ns

Electrical Characteristics (Continued)

 $V_{CC} = 5V$, $T_A = 0^{\circ}C$ to $70^{\circ}C$

Symbol	Parameter	Conditions	Min	Тур	Max	Units
t _{PZH}	Output Enable Time to High				35	ns
	Level					
t _{PZL}	Output Enable Time to Low				30	ns
	Level					
t _{PHZ}	Output Disable Time from				35	ns
	High Level					
t _{PLZ}	Output Disable Time from				30	ns
	Low Level					

Note 1: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics Note 2: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

Note 3: The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A)/\theta_{JA}$. All numbers apply for packages soldered directly into a PC board.

Note 4: ESD rating based upon human body model, 100pF discharged through 1.5k Ω .

Note 5: Voltage limits apply to DI, DE, $\overline{\text{RE}}$ pins.

Note 6: Differential input/output bus voltage is measured at the non-inverting terminal A with respect to the inverting terminal B

Note 7: ΔV_{OD} and $|\Delta V_{OC}|$ are changes in magnitude of V_{OD} and V_{OC} , respectively when the input changes from high to low levels.

Note 8: Applies to both power on and off (ANSI Standard RS-485 conditions)l.

Parameter Measuring Information



FIGURE 1. Test Circuit for V_{OD2} and V_{OC}



FIGURE 2. Test Circuit for V_{OD2}







Parameter Measuring Information (Continued)



FIGURE 5. Test Circuit for Driver T_{PZL} and T_{PLZ}



FIGURE 6. Test Circuit for Receiver V_{OH} and V_{OL}



FIGURE 7. Test Circuit for Receiver T_{PLH} and T_{PHL}

LMS75LBC176





VOLTAGE WAVEFORMS

20047911

FIGURE 8. Test Circuit for Receiver $T_{\text{PZH}}/$ T_{PZL} and $T_{\text{PHZ}}/T_{\text{PLZ}}$

Application Information

POWER LINE NOISE FILTERING

A factor to consider in designing power and ground is noise filtering. A noise filtering circuit is designed to prevent noise generated by the integrated circuit (IC) as well as noise entering the IC from other devices. A common filtering method is to place by-pass capacitors (C_{bp}) between the power and ground lines.

Placing a by-pass capacitor (C_{bp}) with the correct value at the proper location solves many power supply noise problems. Choosing the correct capacitor value is based upon the desired noise filtering range. Since capacitors are not

ideal, they may act more like inductors or resistors over a specific frequency range. Thus, many times two by-pass capacitors may be used to filter a wider bandwidth of noise. It is highly recommended to place a larger capacitor, such as 10 μ F, between power supply pin and ground to filter out low frequencies and a 0.1 μ F to filter out higher frequencies.

By-pass capacitors must be mounted as close as possible to the IC to be effective. Long leads produce higher impedance at higher frequencies due to stray inductance. Thus, this will reduce the by-pass capacitor's effectiveness. Surface mounting chip capacitors are the best solution because they have lower inductance.



FIGURE 9. Placement of by-pass Capacitors, C_{bp}



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